

## **P-Channel Power MOSFET**

-20V, -11A,  $16m\Omega$ 

#### **FEATURES**

- Improved dV/dt capability
- Fast Switching
- Suitable for 1.8V drive applications
- Pb-free plating
- RoHS compliant
- Halogen-free mold compound

#### **APPLICATION**

- Load Switch
- Networking

KEY PERFORMANCE PARAMETERS				
PARAMETER		VALUE	UNIT	
$V_{DS}$		-20	V	
R <sub>DS(on)</sub> (max)	$V_{GS} = -4.5V$	16		
	V <sub>GS</sub> = -2.5V	22	mΩ	
	V <sub>GS</sub> = -1.8V	28		
$Q_{g}$		27	nC	

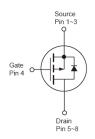












Notes: Moisture sensitivity level: level 3. Per J-STD-020

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	-20	V	
Gate-Source Voltage		$V_{GS}$	±10	V	
Continuous Drain Current (Note 1)	T <sub>C</sub> = 25°C	l <sub>D</sub>	-11	А	
	T <sub>C</sub> = 100°C		-7		
Pulsed Drain Current (Note 2)		I <sub>DM</sub>	-44	Α	
Total Power Dissipation @ T <sub>C</sub> = 25°C		P <sub>DTOT</sub>	2.5	W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	- 55 to +150	°C	

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction to Case Thermal Resistance	$R_{ heta JC}$	25	°C/W	
Junction to Ambient Thermal Resistance	$R_{\Theta JA}$	50	°C/W	

**Notes:**  $R_{\Theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins.  $R_{\Theta JA}$  is guaranteed by design while  $R_{\Theta CA}$  is determined by the user's board design.  $R_{\Theta JA}$  shown below for single device operation on FR-4 PCB in still air.



<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static (Note 3)						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_{D} = -250\mu A$	BV <sub>DSS</sub>	-20			V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	$V_{GS(TH)}$	-0.3	-0.6	-1.0	V
Gate Body Leakage	$V_{GS} = \pm 10V, V_{DS} = 0V$	I <sub>GSS</sub>			±100	nA
Zero Gate Voltage Drain Current	$V_{DS} = -20V, V_{GS} = 0V$	I <sub>DSS</sub>			-1	μA
Drain-Source On-State Resistance	$V_{GS} = -4.5V, I_{D} = -6A$			12	16	mΩ
	$V_{GS} = -2.5V, I_D = -4A$	R <sub>DS(ON)</sub>		16	22	
	$V_{GS} = -1.8V, I_{D} = -3A$	, , ,		21	28	
Dynamic (Note 4)						
Total Gate Charge	$V_{DS} = -10V, I_{D} = -6A,$ $V_{GS} = -4.5V$	$Q_g$		27		
Gate-Source Charge		Q <sub>gs</sub>		2.4		nC
Gate-Drain Charge		$Q_{gd}$		5.3		
Input Capacitance	$V_{DS} = -15V, V_{GS} = 0V,$ f = 1.0MHz	C <sub>iss</sub>	-	2320		
Output Capacitance		C <sub>oss</sub>	-	280		pF
Reverse Transfer Capacitance		C <sub>rss</sub>		175		
Switching (Note 5)						
Turn-On Delay Time	$V_{DD} = -10V,$ $R_{GEN} = 25\Omega,$ $I_{D} = -1A, V_{GS} = -4.5V,$	t <sub>d(on)</sub>		16.2		
Turn-On Rise Time		t <sub>r</sub>		43.5		
Turn-Off Delay Time		t <sub>d(off)</sub>		114		ns
Turn-Off Fall Time		t <sub>f</sub>	-	28.8		
Source-Drain Diode (Note 3)						
Forward On Voltage	I <sub>S</sub> = -1 A, V <sub>GS</sub> = 0V	$V_{SD}$	-		-1	V

#### Notes:

- 1. Current limited by package
- 2. Pulse width limited by the maximum junction temperature
- 3. Pulse test: PW  $\leq$  300 $\mu$ s, duty cycle  $\leq$  2%
- 4. For DESIGN AID ONLY, not subject to production testing.
- 5. Switching time is essentially independent of operating temperature.



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### **ORDERING INFORMATION**

PART NO.	PACKAGE	PACKING
TSM160P02CS RLG	SOP-8	2,500pcs / 13"Reel

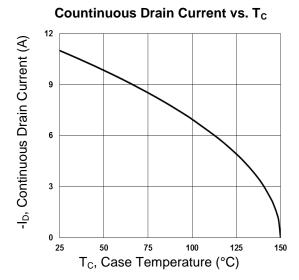
#### Note:

- 1. Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- 2. Halogen-free according to IEC 61249-2-21 definition



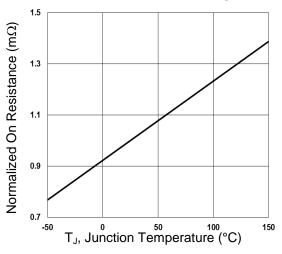
#### **CHARACTERISTICS CURVES**

 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$ 

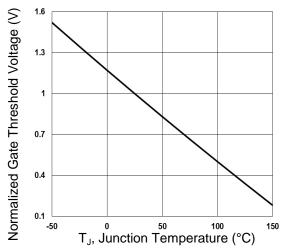


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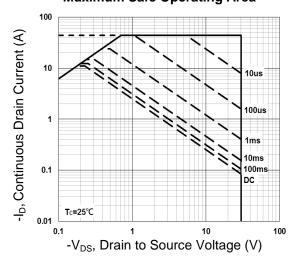
#### **On-Resistance vs. Junction Temperature**



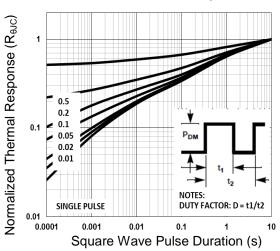




### **Maximum Safe Operating Area**



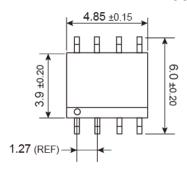
#### **Normalized Thermal Transient Impedance Curve**

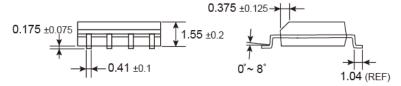




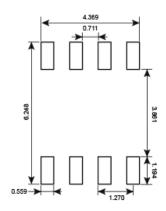
# PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

#### SOP-8

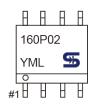




# SUGGESTED PAD LAYOUT



### **MARKING DIAGRAM**



Y = Year Code

**M** = Month Code for Halogen Free Product

 $\mathbf{O}$  =Jan  $\mathbf{P}$  =Feb  $\mathbf{Q}$  =Mar  $\mathbf{R}$  =Apr

S = May T = Jun U = Jul V = Aug

W =Sep X =Oct Y =Nov Z =Dec

 $\mathbf{L}$  = Lot Code (1~9, A~Z)



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